

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SOICHIRO ETO	02/12/2020
HIROYUKI MINEMURA	02/12/2020
TATEHITO USUI	02/12/2020
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION
Street Address:	24-14, NISHI-SHIMBASHI 1-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
Postal Code:	105-8717
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16646790
CORRESPONDENCE DATA	
Fax Number:	(703)610-8686
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7039039000
Email:	ipdocketing@milestockbridge.com, kswanson@milestockbridge.com
Correspondent Name:	ERIC G. KING
Address Line 1:	MILES & STOCKBRIDGE PC
Address Line 2:	1751 PINNACLE DRIVE, SUITE 1500
Address Line 4:	TYSONS CORNER, VIRGINIA 22102
ATTORNEY DOCKET NUMBER:	T6837-23653US01
NAME OF SUBMITTER:	KRYSTAL SWANSON
SIGNATURE:	/Krystal Swanson/
DATE SIGNED:	03/12/2020
Total Attachments: 1	
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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo 105-8717, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

ETCHING APPARATUS AND ETCHING METHOD AND DETECTING APPARATUS OF FILM THICKNESS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Soichiro ETO <u>Soichiro Eto</u>	<u>2020 / 02 / 12</u>
2)	Hiroyuki MINEMURA <u>Hiroyuki Minemura</u>	<u>2020 / 02 / 12</u>
3)	Tatehito USUI <u>Tatehito Usui</u>	<u>2020 / 02 / 12</u>
4)	<u></u>	<u></u>
5)	<u></u>	<u></u>